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ROHM

Constant Current LED Drivers

50V 200mA

1ch Source Driver for Automotive

BD8372HFP-M BD8372EFJ-M

General Description

BD8372HFP-M and BD8372EFJ-M are LED source drivers capable of withstanding high input voltage (50V MAX). The constant current output is set by either of two external resistors. It has built-in LED open/short protection, external resistance open/short protection and overvoltage protection that can achieve high reliability. It is possible to control all LEDs together and turn OFF even if LED causes short/open in a certain row when driving two or more LEDs by using multiple ICs.

Features

- Variable form Constant- Current Source
- H/L Current Setting Switch Control
- LED Open/Short Protection Circuit Integrated
- ISET Open/Short Protection Circuit Integrated
- Overvoltage Mute and Temperature Protection Function Integrated
- Abnormal Output Detection and Output Functions (PBUS)

Applications

Basic Application Circuit

For automotive (Rear lamp, Interior light, etc.).

Key Specifications

- Input Voltage Range:
- Max Output Current:
 - Output Current Accuracy:
 - ccuracy: ±8%(Max)
 - Operating Temperature Range: -
- -40°C to +125°C

5.5V to 40V

200mA(MAX)

Operating remperature Rai

Packages HRP7

HTSOP-J8

W (Typ) x D (Typ) x H (Max) 9.395mm x 10.540mm x 2.005mm 4.90mm x 6.00mm x 1.00mm



HTSOP-J8

VIN VIN UN BD8372HFP-M BD8372EFJ-M FIN STOP PBUS STOP BD8372EFJ-M STOP STOP BD8372EFJ-M STOP STOP BD8372EFJ-M STOP STOP STOP STOP BD8372EFJ-M STOP STOP

Figure 1. Typical Application Circuit

OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

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Pin Configurations



Figure 2. HRP7 Package Pin Configuration

Figure 3. HTSOP-J8 Package Pin Configuration

Pin Descriptions

HRP7		
Pin No.	Pin Name	Description
1	STOP	Input terminal for Brake lamp
2	PBUS	Error detection I/O terminal
3	ISETL	Current setting terminal (L mode)
4	GND	GND
5	ISETH	Current setting terminal (H mode)
6	VIN	Power supply input
7	IOUT	Current output terminal

HTSOP-J	8	
Pin No.	Pin Name	Description
1	VIN	Power supply input
2	IOUT	Current output terminal
3	GND	GND
4	GND	GND
5	STOP	Input terminal for Brake lamp
6	PBUS	Error detection I/O terminal
7	ISETL	Current setting terminal (L mode)
8	ISETH	Current setting terminal (H mode)

Block Diagram



Figure 4. Block Diagram

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol		Symbol		Rating	Unit
Power Supply Voltage		VIN	-0.3 to +50	V		
STOP, IOUT, PBUS Terminal	VSTOP, VIOUT, VPBUS		-0.3 to V _{IN} +0.3	V		
ISETH, ISETL Terminal	VISETH, VISETL		-0.3 to +7	V		
Power Concumption		HRP7	2.3 (Note 1)	14/		
Power Consumption	Pu	HTSOP-J8	1.1 (Note 2)	vv		
Operating Temperature Range	Topr		-40 to +125	°C		
Storage Temperature Range	Tstg		Tstg		-55 to +150	°C
Junction Temperature	Tjmax		150	°C		
IOUT Output Maximum Current		Ιουτ	200	mA		

(Note 1) HRP7

IC mounted on glass epoxy 2-layer board area 15mmx15mm of the back copper foil, measuring 70mmx70mmx1.6mm. Pd decreased at 18.4mw/°C for temperatures above Ta=25°C.

(Note 2) HTSOP-J8

IC mounted on glass epoxy 2-layer board area 15mmx15mm of the back copper foil, measuring 70mmx70mmx1.6mm. Pd decreased at 8.8mW/°C for temperatures above Ta=25°C.

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions (Ta=-40°C to +125°C)

(Please set after considering power consumption for the power-supply voltage.)

Poromotor	Sumbol		Rating	Lloit	Conditions	
Farameter	Symbol	Min	Тур	Max	Unit	Conditions
Power Supply Voltage	V _{IN}	5.5	13	40	V	-
	RISETH	10	-	100	kΩ	STOP=H
Current Setting Resistor	RISETL	10	-	100	kΩ	STOP=L
Minimum Capacitor connecting IOUT terminal	Сюит	0.1	-	-	μF	

Electrical Characteristics

(Unless otherwise specified, Ta=-40°C to 125°C, V_{IN}=13V, R_{ISETL}=R_{ISETH}=40kΩ, R_{PBUS}=10kΩ)

Deremeter	Symbol	Limit		Init	Conditions		
Farameter	Symbol	Min	Тур	Max	Unit	Conditions	
Circuit Current	lin	-	2.9	5	mA		
	1	48.5	50	51.5	mA	50mA setting (I _{SET} =40kΩ) STOP=High, Ta=25°C	
	IOUT_H	46	50	54	mA	50mA setting (I _{SET} =40kΩ) STOP=High, Ta=-40°C to +125°C	
		4.85	5	5.15	mA	5mA setting (I _{SET} =40kΩ) STOP=Low, Ta=25°C	
	IOUT_L	4.6	5	5.4	mA	5mA setting (I _{SET} =40kΩ) STOP=Low, Ta=-40°C to +125°C	
IOUT Drop Voltage H	Vdrh_iout	-	0.7	1.2	V	200mA setting(I _{SET} =10kΩ) STOP=High	
IOUT Drop Voltage L	V _{DRL_IOUT}	-	0.5	0.7	V	20mA setting($I_{SET}=10k\Omega$) STOP=Low	
IOUT OFF Current	IOUT_OFF	-	-	1	μA	V _{IOUT} =2V, PBUS=L, Ta=25°C	
IOUT Current at GND Short	IOUT_SHORT	-	-	40	μA	V _{IOUT} =0V	
ISET Terminal Voltage	VISET	-	0.8	-	V	At ISETL or ISETH pins	
ISET Short Detection Resistor	RISET_SHORT	-	5.1k	7.5k	Ω	At ISETL or ISETH pins	
ISET Open Detection Resistor	RISET_OPEN	125k	400k	-	Ω	At ISETL or ISETH pins	
IOUT LED OPEN Detection	VIOUT_OPEN	V _{IN} -0.3	V _{IN} -0.2	V _{IN} -0.1	V		
IOUT LED Short Detection	VIOUT_SHORT	0.2	0.6	1.0	V		
STOP Input Voltage H	VIH_STOP	4.0	-	V _{IN} +0.2	V		
STOP Input Voltage L	VIL_STOP	GND	-	1.0	V		
STOP Input Current	VIN_STOP	-	40	100	μA	V _{STOP} =13V	
PBUS Input Voltage H	VIH_PBUS	4.0	-	V _{IN} +0.2	V		
PBUS Input Voltage L	VIL_PBUS	GND	-	2.0	V		
PBUS Low Voltage	V _{OL_PBUS}	-	-	1.5	V	IPBUS=20mA	
PBUS Input Current	IIN_PBUS	-	38	100	μA	V _{PBUS} =13V	
IN Under Voltage Open Detection Mask Voltage	VUVLO_IOPEN	7.5	8.0	8.5	V		
IN Over Voltage Mute Current	VIN_OVPMUTE	16	19	24	V	200mA setting (I _{SET} =10kΩ) STOP=High	

Typical Performance Curves (Reference Data)

(Unless otherwise specified Ta=25°C, VIN=13V)



Typical Performance Curves (Reference Data) - continued

(Unless otherwise specified Ta=25°C, VIN=13V)



Timing Chart







Function Description

(Unless otherwise specified, Ta=25°C, V_{IN} =13V, R_{ISETL} = R_{ISETH} =40k Ω , the numerical value in the table are TYP values.)

1. Table for Operation

STOP	VIOUT	RISETL	RISETH	MODE	Ιουτ	PBUS
L	2V <v<sub>IOUT <vin-0.7v(max)< td=""><td>10kΩ≤R_{ISETL} ≤100kΩ</td><td>-</td><td>L mode normal operation</td><td>2mA to 20mA</td><td>Hi-Z</td></vin-0.7v(max)<></v<sub>	10kΩ≤R _{ISETL} ≤100kΩ	-	L mode normal operation	2mA to 20mA	Hi-Z
н	2V <v<sub>IOUT <v<sub>IN-1.2V(Max)</v<sub></v<sub>	-	10kΩ≤R _{ISETH} ≤100kΩ	H mode normal operation	20mA to 200mA	Hi-Z
L/H	V _{IOUT} ≤0.6V(Typ)	-	-	Output short	40µA(Max)	LOW output
L/H	V _{IOUT} ≥ V _{IN} -0.2V(Typ)	-	-	Output open	1µA(Max)	LOW output
L	-	R _{ISETL} <7.5kΩ(Max)	-	ISETL short	1µA(Max)	LOW output
L	-	R_{ISETL} >125k Ω (Min)	-	I _{SETL} open	1µA(Max)	LOW output
н	-	-	R _{ISETH} <7.5kΩ(Max)	I _{SETH} short	1µA(Max)	LOW output
н	-	-	R _{ISETH} >125kΩ(Min)	Isetн open	1µA(Max)	LOW output
L	2V <v<sub>IOUT <v<sub>IN-0.7V(Max)</v<sub></v<sub>	10kΩ≤R _{ISETL} ≤100kΩ	-	PBUS control OFF	1µA(Max)	LOW input
н	2V <v<sub>IOUT <v<sub>IN-1.2V(Max)</v<sub></v<sub>	-	10kΩ≤Rıseth ≤100kΩ	PBUS control OFF	1µA(Max)	LOW input

Protection Mode Operation Voltage(The numerical value are typical)

VIN	LED open	LED short	ISET open	ISET short	PBUS	Overvoltage protection
5.5V <v<sub>IN≤8V</v<sub>	×	0	0	0	0	×
8V≤V _{IN} ≤19V	0	0	0	0	0	×
19V≤V _{IN}	0	0	0	0	0	0

O : Protection mode ON

 $\times\,$: Protection mode OFF

The LED open function is masked with V_{IN} \le 8V.

2. Method of Setting Current

The IC regulates the voltage at ISETL/ISETH to V_{ISET} (0.8V typ) across the external resistor to set I_{OUT} . Then I_{OUT} is set by setting STOP High or Low.







• L mode (STOP=Low)

$$I_{IOUT} = \frac{0.8V}{R_{ISETL}} \times 250A$$

exp)
$$R_{ISETL} = 1.6k\Omega$$
 $I_{IOUT} = \frac{0.8V}{40k\Omega} \times 250 = 5mA$

$$I_{IOUT} = \frac{0.8V}{R_{ISETH}} \times 2500A$$

exp)
$$R_{ISETH} = 40k\Omega$$
 $I_{IOUT} = \frac{0.8V}{40k\Omega} \times 2500 = 50mA$

3. Current Control at Output Saturation

When V_{IOUT} (=V_F) - V_{IN} > 0.5V (TYP), the LED current I_F is decreased to a set current 20µA (TYP). Therefore, V_F decreases due to the decrease in the current. Open detection can be prevented by keeping $V_{IOUT} \le V_{IN}$ -0.5V. The current controlled to $I_{OUT} \le 20\mu$ A and the LED current I_F must be set so that V_F does not exceed V_{UVLO_OPEN} by 20µA. If $V_{IN} < V_{UVLO_OPEN}$ this function is not active.





Figure 15. Current Control at Output Saturation

4. PROTECT BUS (PBUS)

PBUS is an I/O terminal that outputs any detected error by switching PBUS from Hi-Z (Note 1) to Low. The output current can also be turned OFF by pulling the PBUS Low. When driving multiple LEDs through multiple ICs, as shown in the figure below, all the rows of LEDs can be turned OFF by any fault by connecting PBUS terminal to each IC. (Note1) PBUS terminal is an open drain terminal. Even when used separately, please be pulled $up(10k\Omega)$ to power supply voltage.



Figure 16. PBUS Function

• Example of operating protection for an LED open condition





When LED becomes open on the first IC, PBUS of IC1 is switched from Hi-Z to Low. As PBUS becomes Low, the other ICs detect the error and turns OFF their own LEDs. V_{IOUT} clamps to 1.4V during the OFF period in order to prevent ground short protection.

Oper ×

(2) LED Short Detecting Function

IC heating and the PBUS is pulled LOW.

5. Protection Function

This IC has built-in short/open protection function for the external components. Any error detected will pull the PBUS terminal low.

(1) LED Open Detecting Function When any LED connected at the IOUT becomes open, VIOUT will go HIGH. When an error is detected at VIOUT < VIOUT_OPEN the PBUS is pulled LOW.

When the LEDs connected at the IOUT terminal are shorted to ground, VIOUT will go LOW. When an error is detected at VIOUT <

VIOUT_SHORT 0.6V (TYP) the output current is turned OFF to prevent

Ý Figure 18. LED Open detection function

PBU



Current Control

Figure 19. LED Short detection function



Figure 20. ISET Pin open detection function



Figure 21. ISET Pin short detection function

(3) ISET(H/L) Open Detecting Function When the external resistance connected at ISETL or ISETH terminal > RISET_OPEN 400k (TYP), the output current is turned OFF to prevent IC heating and the PBUS is pulled LOW. This detection is not affected by the current setting mode.

(4) ISET(H/L) Short Detecting Function When the external resistance connected at ISETL or ISETH terminal < R_{ISET_SHORT} 5.1k (TYP), the output current is turned OFF to protect the LEDs and the PBUS is pulled LOW. This detection is not affected by the current setting mode.

6. Over Voltage Protection

Overvoltage protection works in (R_{ISETH} =40k Ω), 18V (TYP) \leq V_{IN} at I_{OUT}=200mA setting and limits output current to suppress the upswing in heat generation of LSI.

The overvoltage mute protection is effective only for (STOP=High) at H mode time.



Figure 22. Overvoltage mute function

Recommended application circuit



Figure 23. Recommended application circuit

(Note) EMC ISO 11452-2 (ALSE) ISO 11452-4 (BCI) ISO 7637-2

· pulse1

Pulse2a,2b (level4)

• Pulse3a,3b (level4)

No.	Component Name	Component Value	Product Name	Company
1	D1	-	RF201L2S	ROHM
2	D2	-	RF201L2S	ROHM
3	D3	-	RF201L2S	ROHM
4	ZD1	-	TNR12H-220K	NIPPON CHEMICON
5	FL1	-	HMZ2012R102A	TDK
6	Cvin	4.7µF	GCM32ER71H475KA40	murata
7	Сюлт	0.1µF	GCM188R11H104KA42	murata
8	CSTOP	0.1µF	GCM188R11H104KA42	murata
9	RISETL	39kΩ	MCR03 Series	ROHM
10	RISETH	39kΩ	MCR03 Series	ROHM
11	RPBUS	10kΩ	MCR03 Series	ROHM
12	R1	10kΩ	MCR03 Series	ROHM
13	R2	10kΩ	MCR03 Series	ROHM

Table 1. BOM List

Power Dissipation

HRP7 Package



HTSOP-J8 Package



(Caution1) When mounted with 70.0mm x 70.0mm x 1.6mm glass epoxy substrate.

(Caution2) Abobe copper foil area indicates backside copper foil area.

(Caution3) Value changes according to number of substrate layers and copper foil area. Note that this value is a measured value. Not a guaranteed value.

Figure 24. Thermal Dissipation Curve

Pd (Power dissipation) and I_{OMAX} (Permissible current)

The relation between Pd and IOMAX by VF of LED connected with IOUT is shown.



Figure 25. Heat reduction curve

I/O Equivalent Circuit

Pin No.	Pin Name	I/O Equivalent Circuit
1	STOP	VIN (6pin) STOP (1pin) GND (4pin) STOP (4pin) STOP STOP (1pin) ST
2	PBUS	$(6pin) \longrightarrow 200k \Omega$ $(28pin) \longrightarrow 5V$ $(28pin) \longrightarrow 5V$ $(4pin) \longrightarrow 5V$
3	ISETL	VIN (6pin) ISETL (3pin) GND (4pin)
4	GND	-

I/O Equivalent Circuit – continued

Pin No.	Pin Name	I/O Equivalent Circuit
5	ISETH	VIN (6pin) ISETH (5pin) GND (4pin)
6	VIN	-
7	IOUT	VIN (6pin) IOUT (7pin) GND (4pin)

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. **Testing on Application Boards**

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

Operational Notes – continued

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



Figure 26. Example of monolithic IC structure

13. Thermal Shutdown Circuit(TSD)

This IC has a built-in thermal shutdown circuit that prevents heat damage to the IC. Normal operation should always be within the IC's power dissipation rating. If however the rating is exceeded for a continued period, the junction temperature (Tj) will rise which will activate the TSD circuit that will turn OFF all output pins. When the Tj falls below the TSD threshold, the circuits are automatically restored to normal operation.

Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

14. Sudden Voltage Surge on VIN

Because MOSFETs are used in the output, a very steep change in the VCC voltage may cause the transistors to conduct large current. Take this condition into account when selecting the value of external circuit constants for a certain application.



Marking Diagrams



Part Number Marking	Package		Part Number
BD8372HFP	HRP7	Reel of 2000	BD8372HFP-MTR
BD8372	HTSOP-J8	Reel of 2500	BD8372EFJ-ME2

Datasheet





Physical Dimension, Tape and Reel Information - continued Package Name HTSOP-J8 4. 9 ± 0.1 include. BURR) Max5.25 (3. 2) $4^{\circ} + 6^{\circ}_{-4^{\circ}}$ 8 7 6 5 2 -4) 0±0. $9 \pm 0.$ 65 ± 0.15 (2. 2 6. 3. $0.5 \pm 0.$ Γ. 0. 2 1 3 4 1PIN MARK 0.545 $0.\ 1\ 7\ {}^{+0.}_{-0.}\ 0\ {}^{05}_{03}$ S OMAX 1. 05 08 $85\pm0.$ 08±0. 0. $42 \stackrel{+0.}{_{-0.}04} 05 \oplus 0.08 \mathbb{M}$ 1. 27 (UNIT:mm) \bigcirc 0. 08 S 0. 0. PKG:HTSOP-J8 Drawing No. EX169-5002-2 <Tape and Reel information> Embossed carrier tape Таре 2500pcs Quantity E2 Direction The direction is the 1pin of product is at the upper left when you hold of feed reel on the left hand and you pull out the tape on the right hand Direction of feed 1pin Reel *Order quantity needs to be multiple of the minimum quantity.

Revision History

Date	Revision	Changes
09.Dec.2015	001	New Release